

AMENDMENTS TO THE SPECIFICATION:

Please amend the paragraph starting at line 25 on page 1 as follows:

A structure of a package fabricated by the prior art flip chip bonding is illustrated in Fig. 1. For both or one of a semiconductor chip 1 and a wiring substrate 2, terminal electrodes [[12]] are prepared by forming bumps 4 of gold or solder material in advance. The semiconductor chip 1, having its terminal pads at the bottom, is aligned in position onto the wiring substrate 2, and then subjected to heating and pressing treatments for connecting terminals and securing the chip_1. Clearances between the chip 1 and the wiring substrate 2 are sealed with resin 3, as required.